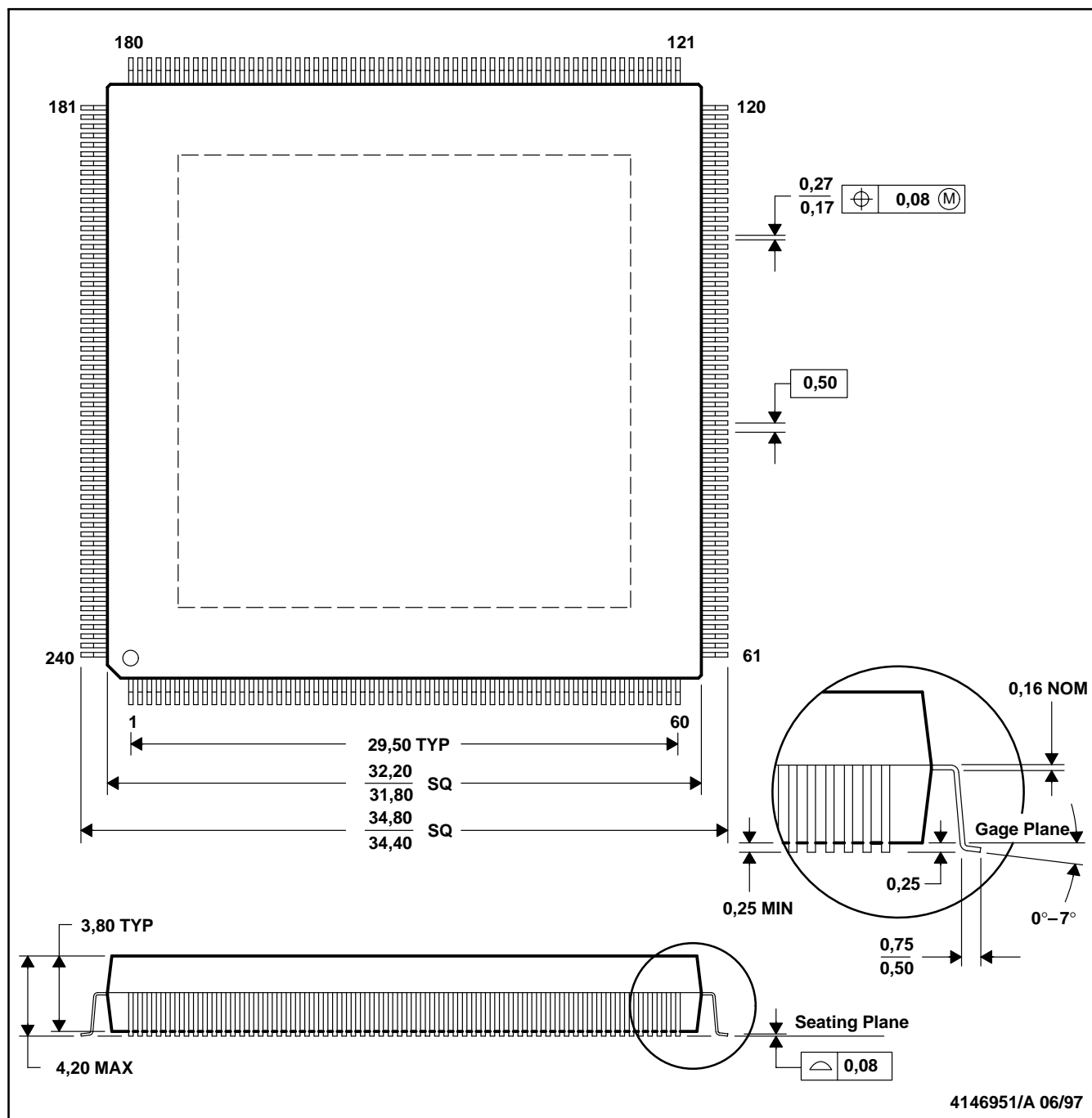


PGW (S-PQFP-G240)

PLASTIC QUAD FLATPACK



NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Thermally enhanced molded plastic package with a exposed heat slug (HSL) on bottom.

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